

**HIGH DENSITY PRINTED WIRING BOARD HAVING IN-VIA
SURFACE MOUNTING PADS**

Abstract

A multilayer printed wiring board in which surface contact pads are formed by depositing electrically conductive metallic layers directly over blind holes/vias. This allows ball grid array devices to be mounted on the printed wiring boards with a greater contact pad density than is the case where the contact pads are formed to the sides of the blind holes/vias. In a method of manufacturing printed wiring boards embodying the invention, it is desirable to treat the surfaces of the board to prepare the outward facing surfaces of the plated layers of the blind vias to receive copper capping layers.